04/10/03 #5C (4/8)

CERTIFICATE OF MAILING UNDER 37 C.F.R. 1.10

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Box AF, Assistant Commissioner for Patents, Washington, D.C. 20231 on March 31, 2003.

Signed: *Laura Lee Mosier*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: SAVAGE *et al.*		Examiner:	FOX, Charles A.
Application No.	09/767,659	Art Unit:	3652
Filed:	January 22, 2001	Date:	March 31, 2003
For:	Semiconductor Wafer Processing System with Vertically-Stacked Process Chambers and Single-Axis Dual Wafer Transfer System		

AMENDMENT AFTER FINAL

Box AF
Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

This Amendment is responsive to the final Office Action mailed December 31, 2002.

Please amend the application as follows:

In the Claims:

Please amend claims 19 and 24 to read as shown:

19. (Amended) A method of semiconductor wafer processing comprising the steps of:

providing a multi-chamber module including a plurality of vertically-stacked semiconductor wafer process chambers;

providing a loadlock chamber for each of the vertically-stacked semiconductor wafer process chambers, wherein each loadlock chamber having a transfer arm including an upper wafer shelf for carrying unprocessed wafers and a lower wafer shelf for carrying processed wafers, and a semiconductor wafer process chamber;